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W. HART

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): T. HIROSE, et al  
Serial No.: 09/800,495  
Filed: March 8, 2001  
For: METHOD OF DETECTING AND MEASURING ENDPOINT OF  
POLISHING PROCESSING AND ITS APPARATUS AND  
METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE  
USING THE SAME  
Group: 3723  
Examiner: D. Nguyen

AMENDMENT

Commissioner for Patents  
Washington, D.C. 20231

July 8, 2002

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Sir:

The following amendments and remarks are respectfully submitted in connection with the above-identified application in response to the Office Action dated June 6, 2002.

IN THE CLAIMS:

Please amend claim 1 as follows:

- Sub 1
1. (amended) A method of detecting an endpoint of polishing processing, comprising the steps of:
- concurrently irradiating a film formed on a surface of a wafer under polishing processing with light having two or more different wavelengths;
  - detecting reflected lights from said film caused by the irradiation; and
  - detecting the endpoint of polishing processing of said film on the basis of a relationship between intensities of the detected reflected lights.
- A1